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Aberrant photoelectric effect in the topological insulator/n-GaN heterojunction ($\text{Bi}_2\text{Te}_3/\text{n-GaN}$) under unpolarized illumination

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1. Fabrication flow process diagram

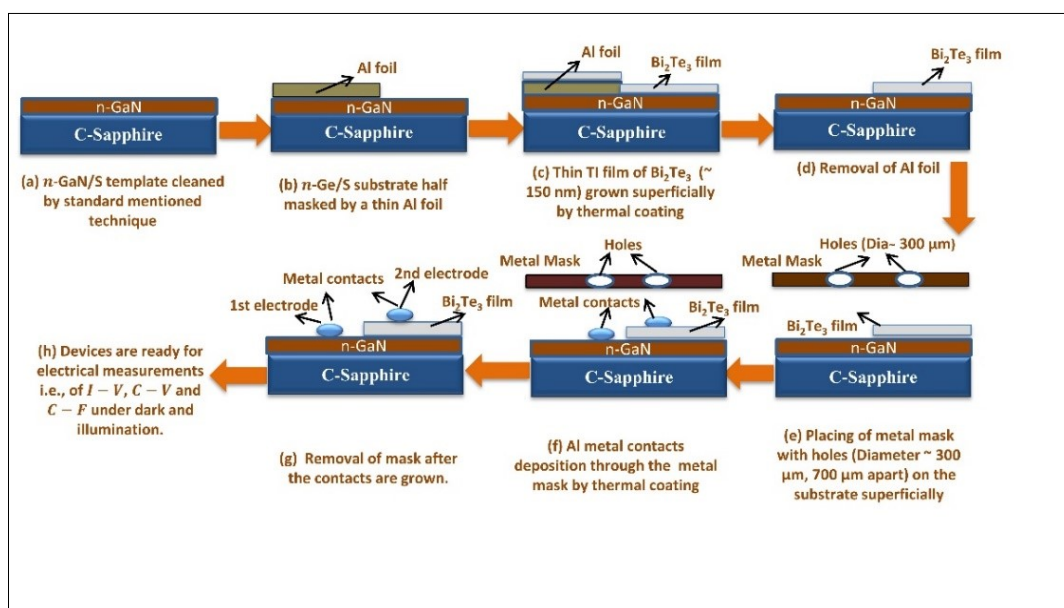


Figure S1 Flow diagram depicting the steps involved in the fabrication process of $\text{Bi}_2\text{Te}_3/\text{n-GaN}$ heterostructure.

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† No conflict of interest from any of the authors.

2. Material and microstructure study of the Bi_2Te_3 TI film grown on $n\text{-GaN}$ Substrate

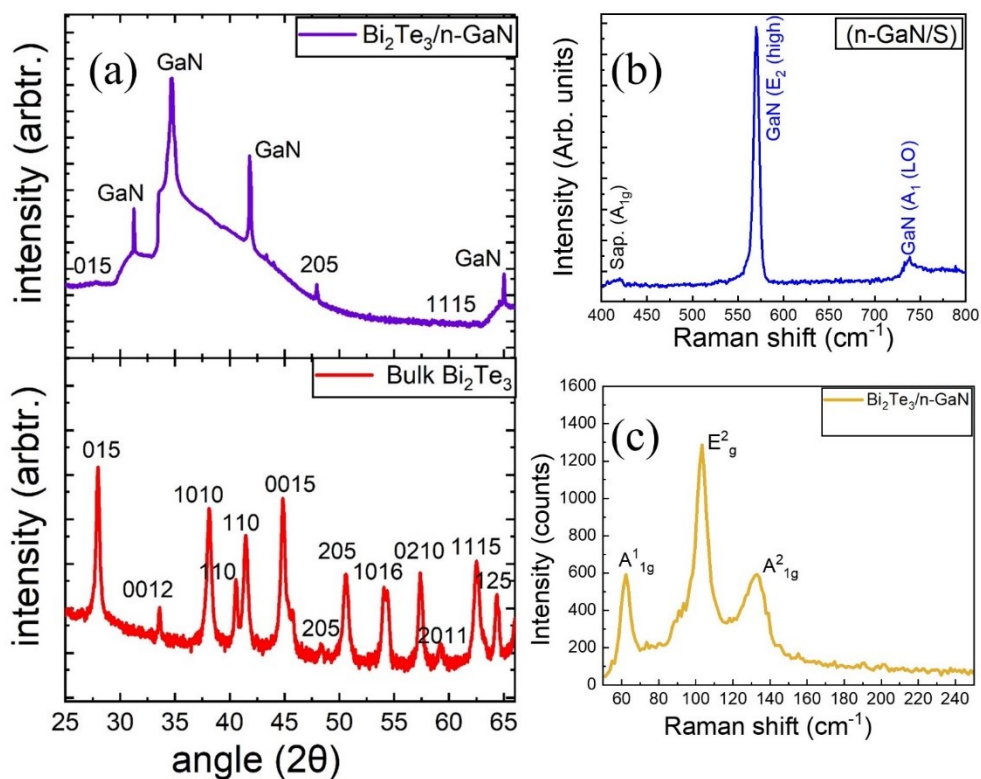


Figure S2 (a) Shows the result of XRD of $\text{Bi}_2\text{Te}_3/n\text{-GaN/S}$ and the bulk Bi_2Te_3 (b) Shows the Raman spectroscopy results of $n\text{-GaN/S}$ (c) Shows the Raman spectroscopy results of $n\text{-GaN/Bi}_2\text{Te}_3/\text{S}$.

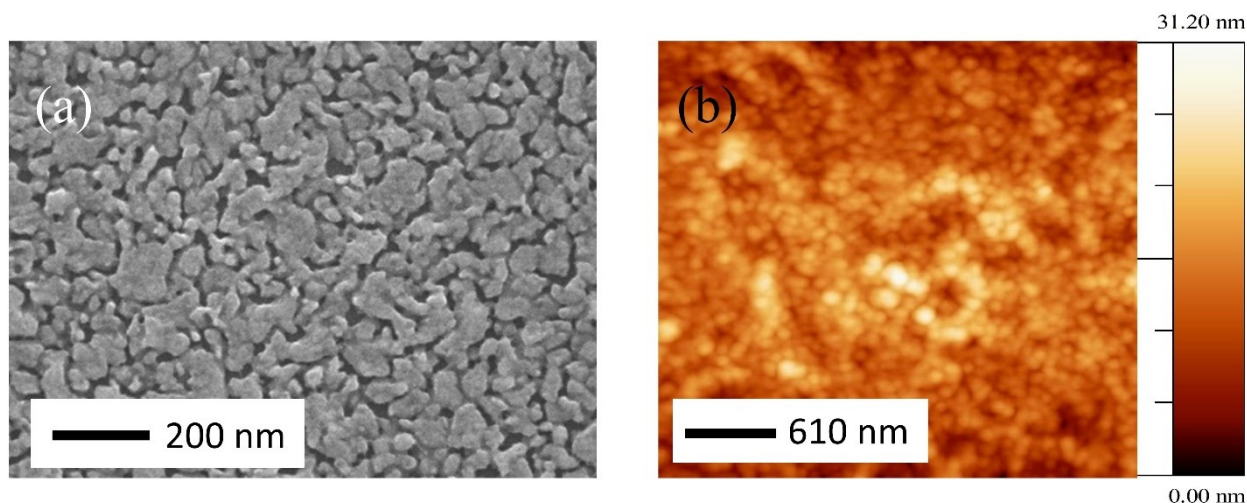


Figure S3 shows the SEM image of the grown Bi_2Te_3 film grown on $n\text{-GaN/S}$ (b) Shows the AFM micrograph of the Bi_2Te_3 TI film on $n\text{-GaN/S}$ substrate.

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Figure S2a shows the XRD results of Bi_2Te_3 TI film grown on n -GaN template (sapphire). XRD peak of Bi_2Te_3 TI film in the $\text{Bi}_2\text{Te}_3/n$ -GaN heterostructure revealed the polycrystalline rhombohedral structure [space group R-3m (166)]. The XRD peaks obtained conforms with the results of the bulk Bi_2Te_3 compound. The peaks were being matched with the standard International Center for diffraction Data (ICDD) having Portable Document Format (PDF) card No. 00-002-0524. Raman spectroscopy for n -GaN/Sapphire(S) template (Figure S2c), showed the peak of strong E_2 transverse optical (TO) mode and A_1 longitudinal optical (LO) modes observed at 570 cm^{-1} and 738 cm^{-1} with a little shifting of the A_1 (LO) mode for the n -GaN/S as observed earlier¹. The small peak of the sapphire substrate was obtained at 420 cm^{-1} representing the A_{1g} active mode which was found consistent with the earlier results². For the $\text{Bi}_2\text{Te}_3/n$ -GaN heterostructure peaks at 62.3 cm^{-1} , 103.3 cm^{-1} and 133.0 cm^{-1} were obtained representing the A_{1g}^{LO} , E_g^{TO} , and A_{1g}^{LO} active modes. The peaks obtained were sharp and quite similar to the previous results of grown

Bi_2Te_3 film on GaN^3 . A little shifting in the wavenumber of the peaks was seen which may be due to a small defect during the grown process of the Bi_2Te_3 film³. Figure S3a shows the SEM micrograph image of the Bi_2Te_3 film on the GaN/S template, confirming the porosity of the film with the size of the grain between the range $\sim 70\text{-}80\text{ nm}$. AFM image of the Bi_2Te_3 film on GaN/S template in Figure S3b, revealed the root mean square roughness (RMS) = 3.8088 nm and average roughness = 3.7908 . The RMS roughness revealed the uniformity of the film which is a requisite for optimum conductivity and good performance of the devices. Small surface roughness also ascertains the minimum interface state density (D_{it})⁴ at the contact junction with the Bi_2Te_3 film which is suitable for the device. The porous nature of the film, observed from the SEM image was due to the growth process of Thermal coating⁵.

3. $I-V$ study of the $\text{Bi}_2\text{Te}_3/n$ -GaN heterojunction and the Bi_2Te_3 TI film

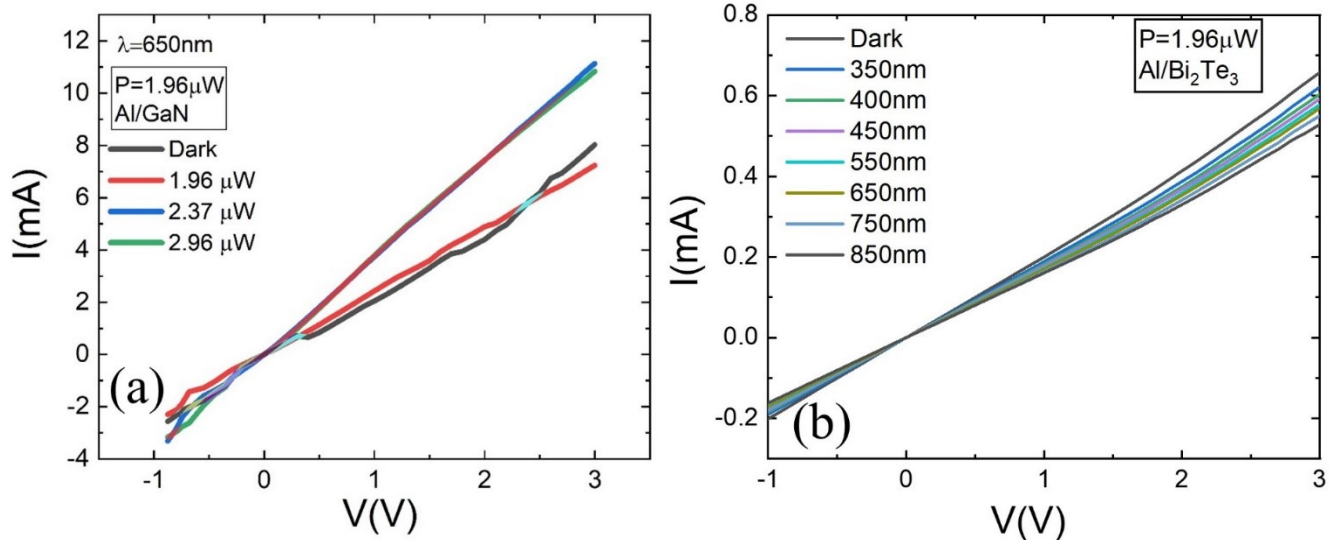


Figure S4 (a) shows the $I-V$ results obtained through Al metallic contacts on the n -GaN template which was observed to be ohmic and conducting in both positive and negative biasing for wavelength ($\lambda = 650\text{ nm}$) and incident power (P at $1.96\text{ }\mu\text{W}$, $2.37\text{ }\mu\text{W}$ and $1.96\text{ }\mu\text{W}$) (b) $I-V$ results measured through the Al metal contacts on the Bi_2Te_3 TI film grown on the n -GaN template, under the dark and illumination conditions for λ varied from 350 nm to 950 nm , at $P=1.96\text{ }\mu\text{W}$.

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We annealed the devices $\text{Bi}_2\text{Te}_3/n\text{-GaN}$ after the contact deposition in the range of 200-300 °C for 1- 2 h to ensure the ohmic contacts. Figure S4a shows the results in both the positive and negative biasing in opposite quadrant which confirmed the ohmic behaviour and exclude the depletion layer affect. The results in Figure S4a showed the consistent results obtained for wavelength (λ) = 650 nm and incident power (P) at 1.96 μW , 2.37 μW and 1.96 μW .

4. Semi log (I-V) and plot Extraction of ideality factor

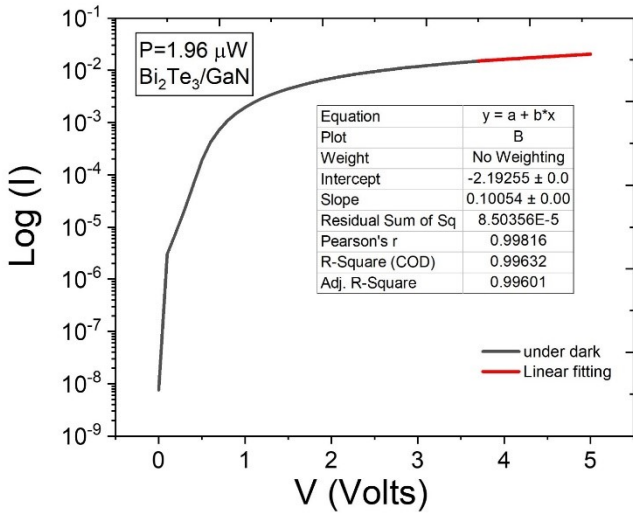


Figure S5 Shows the Semi-log (I-V) plot and its linear fitting in the saturation region.

In forward-bias, $I-V$ characteristics of a diode is given by the Eq. S1 as:

$$I = I_R \left(e^{\frac{qV}{nkT}} - 1 \right) \quad (\text{S1})$$

I_R is the reverse saturation current

k is the Boltzmann constant

T is the temperature in Kelvin, q is the electronic charge

Assuming $V \gg \frac{kT}{q}$ (Thermal Voltage) the Eq. 1 can be

$$n \cong \frac{q}{kT} \frac{1}{\frac{d \ln I}{dV}} \quad (\text{S2})$$

Calculating from the Eq. S2 by taking the slope of the Semi-log (I-V) characteristics (Figure S5) at the saturation voltage we get the ideality factor as $n \approx 3.88$.

5. 2-Diode Simulation for extracting the $n\text{-GaN}/\text{Bi}_2\text{Te}_3$ heterojunction device parameters under the dark and illumination conditions

The experimental $I-V$ results of the $\text{Bi}_2\text{Te}_3/n\text{-GaN}$ heterojunction were used for simulating by 2-diode model^{6,7}. $I-V$ characteristics of solar cell heterojunction devices are represented by a single diode, but more circuit elements are required to study the behaviour in a much more precise way, which requires a 2-diode circuit model^{6,7} which is shown in Figure S6. In Figure S6, $J(V)$ and V represents the current and voltage at the contacts. R_{pp} , R_{ss} are the ohmic parallel and series resistance included in junction devices⁷, representing all the contributing currents i.e. diffusion, recombination, and ohmic⁷. The diode D_{01} represents the diffusion current $J_d(V)$, D_{02} represents the recombination current $J_r(V)$, in the depletion region⁸. J_{ph} is the photocurrent in the circuit (J_{ph})⁸ which is assumed zero because of the dark conditions of measurements. Therefore, the dark current represented by the 2-diode model Equation (S1): -

$$J(V) = J_{01} \left(e^{\frac{qV}{n_1 kT}} - 1 \right) + J_{02} \left(e^{\frac{qV}{n_2 kT}} - 1 \right) = J_d(V) + J_r(V) \quad (\text{S1})$$

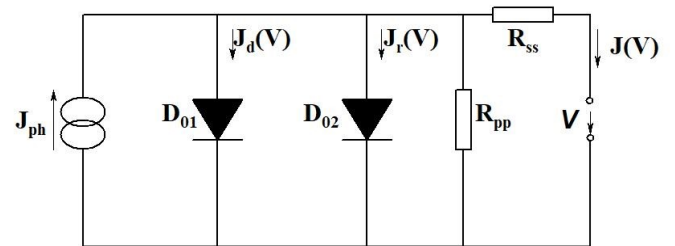


Figure S6 An equivalent 2-diode model circuit⁶ was used for the simulation of the $n\text{-GaN}/\text{Bi}_2\text{Te}_3$ heterojunctions under dark and illuminated conditions at room temperature (300 K).

J_{01} and J_{02} is the pre-exponential coefficient of $J_d(V)$ and $J_r(V)$. J_{01} is the recombination current occurring in the bulk, dominant usually at higher bias⁸ J_{02} denotes the saturation current density due to depletion region recombination at the junction which is dominant at lower bias⁸. n_1, n_2 is the ideality factor for the diode D_{01} and D_{02} ^{8,6}. The ideal value of n_1 is 1, if the carrier lifetime is independent of the minority carrier concentration⁹. The ideal value of n_2 is 2⁹. The 2-diode model was used to fit and extract find out various parameters such as $J_{01}, J_{02}, n_1, n_2, R_{pp}$ and R_{ss} ⁷. Current here is expressed as current densities, which makes it independent of the cell area. R_{ss} is also expressed in $\Omega\text{-cm}^2$. Our device's area is 0.0049 cm^2 , which is the area between the consecutive Al contacts (Figure 1 in the manuscript). The simulated parameters give insight into the recombination of charge carriers as well as about the efficiency of $\text{Bi}_2\text{Te}_3/n\text{-GaN}$ heterojunction devices when employed in electronics devices, particularly in solar cells¹⁰. The efficiency of solar cell devices was seen to be limited due to the various

recombination of electrons such as depletion-region recombination, edge recombination, and resistance-limited recombination, as seen in previous studies⁹. Figure S7a shows the Current density-Voltage ($J-V$) and the local ideality factor ($n-V$) plot obtained by the 2-diode simulation fitting for the experimental $I-V$ results of the $\text{Bi}_2\text{Te}_3/n\text{-GaN}$ heterojunction under the dark conditions. Whereas the individual characteristics for the D_{01}, D_{02} diodes, series resistance (R_{ss}) and parallel resistance R_{pp} is also shown, as obtained from the fittings. The $J-V$ well fitted with the experimental results obtained with the ideality factor obtained as $n = 3.0138$. Figure S7b & S7c shows the series resistance (R_{ss}) and parallel resistance R_{pp} shows almost the same decreasing behavior with the increase in the incident photon energy of the light. This represents the behavior of the $\text{Bi}_2\text{Te}_3/n\text{-GaN}$ heterojunction devices after the illumination where the series resistance decreases with the increase in the incident photon energy of the light. This behavior was also evident from the $I-V$ characteristics of the $\text{Bi}_2\text{Te}_3/n\text{-GaN}$ heterojunction devices at constant incident power (Figure 2 in the Manuscript).

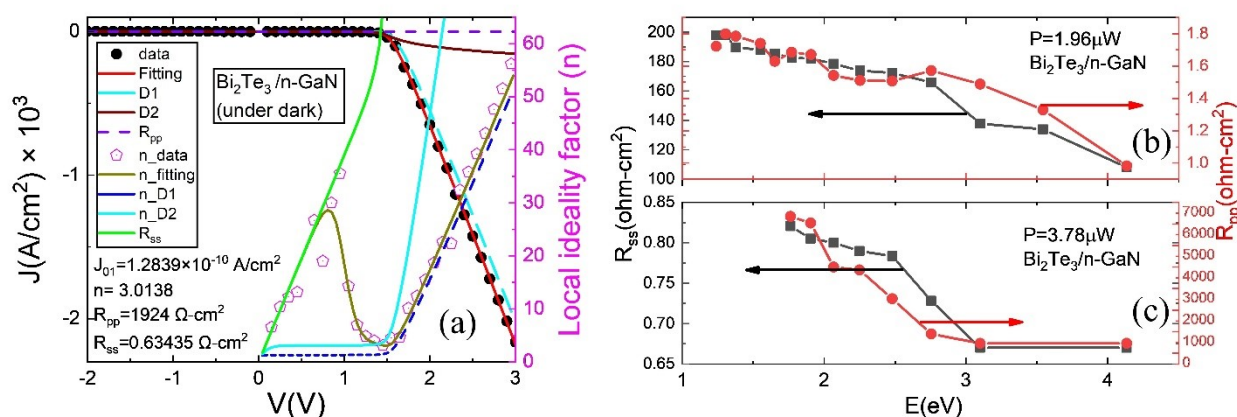


Figure S7 (a) Shows the current density-voltage ($J-V$) and the local ideality factor ($n-V$) plot obtained by the 2-diode simulation fitting for the experimental $I-V$ results of the $\text{Bi}_2\text{Te}_3/n\text{-GaN}$ heterojunction under the dark conditions with individual characteristics for the D_{01}, D_{02} diodes and parallel resistance R_{pp} (b) Shows the series resistance (R_{ss}) the parallel resistance (R_{pp}) plot versus the incident light energy (E) for the $\text{Bi}_2\text{Te}_3/n\text{-GaN}$ heterojunction under illumination at the incident power of (b) $1.96\ \mu\text{W}$ and (c) for $3.78\ \mu\text{W}$

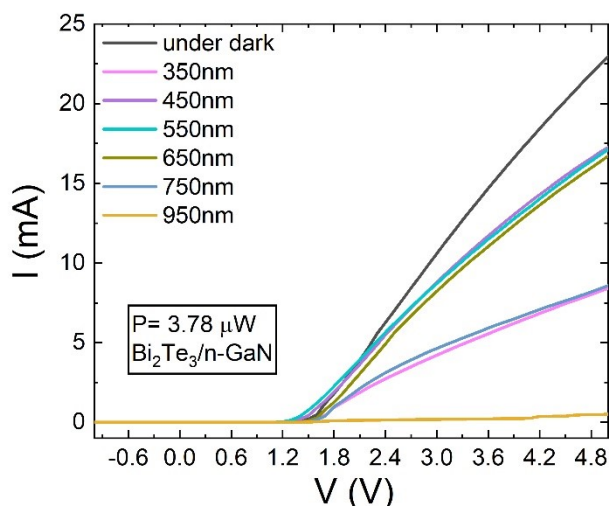


Figure S8 Shows the $I-V$ characteristics for the $\text{Bi}_2\text{Te}_3/n\text{-GaN}$ heterojunction device under the dark and illumination conditions when the wavelength of the incident light was varied from 350 nm to 950 nm under the constant incident light power of $3.78 \mu\text{W}$

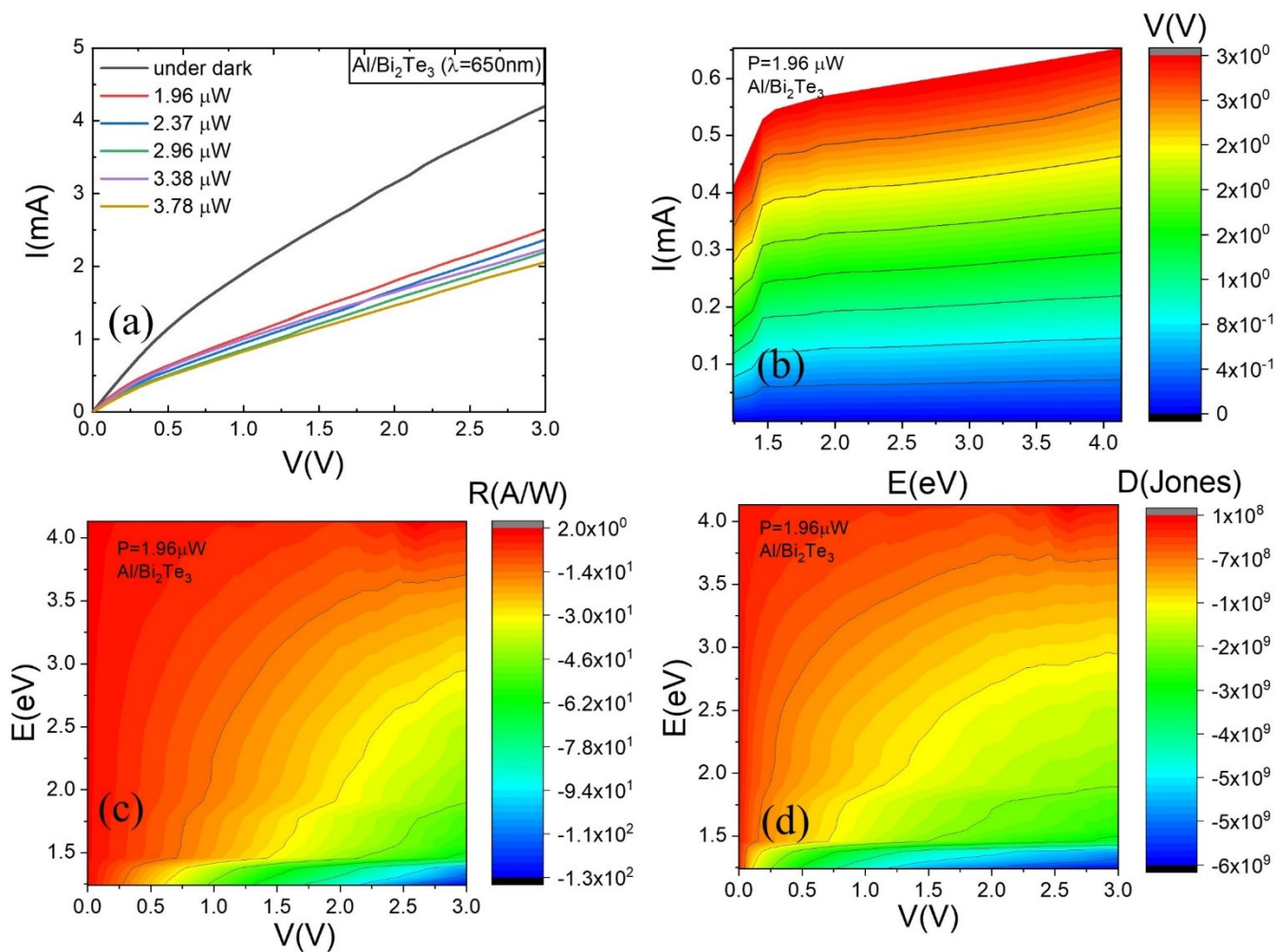


Figure S9 (a) Shows the $I-V$ characteristics measured through the Al contacts on the Bi_2Te_3 TI film on $n\text{-GaN}$ template at a constant incident light of wavelength (λ) = 650 nm with power (P) varying from $1.96 \mu\text{W}$ - $3.78 \mu\text{W}$

(b) shows the contour plot of current-voltage ($I - V$) versus the incident photon light energy (E) in eV at a constant power of $1.96 \mu W$ (c) shows the contour plot of energy-responsivity ($E - R$) versus the bias voltage (V) measured through the Al contacts, at constant $1.96 \mu W$ incident power (d) The energy-detectivity ($E - D$) versus the bias voltage (V) plot measured through the Al contacts at $1.96 \mu W$ incident power.

5. Capacitance-frequency ($C - f$), ($G_p/\omega - \omega$) plot under dark and illumination and optical parameters measurements

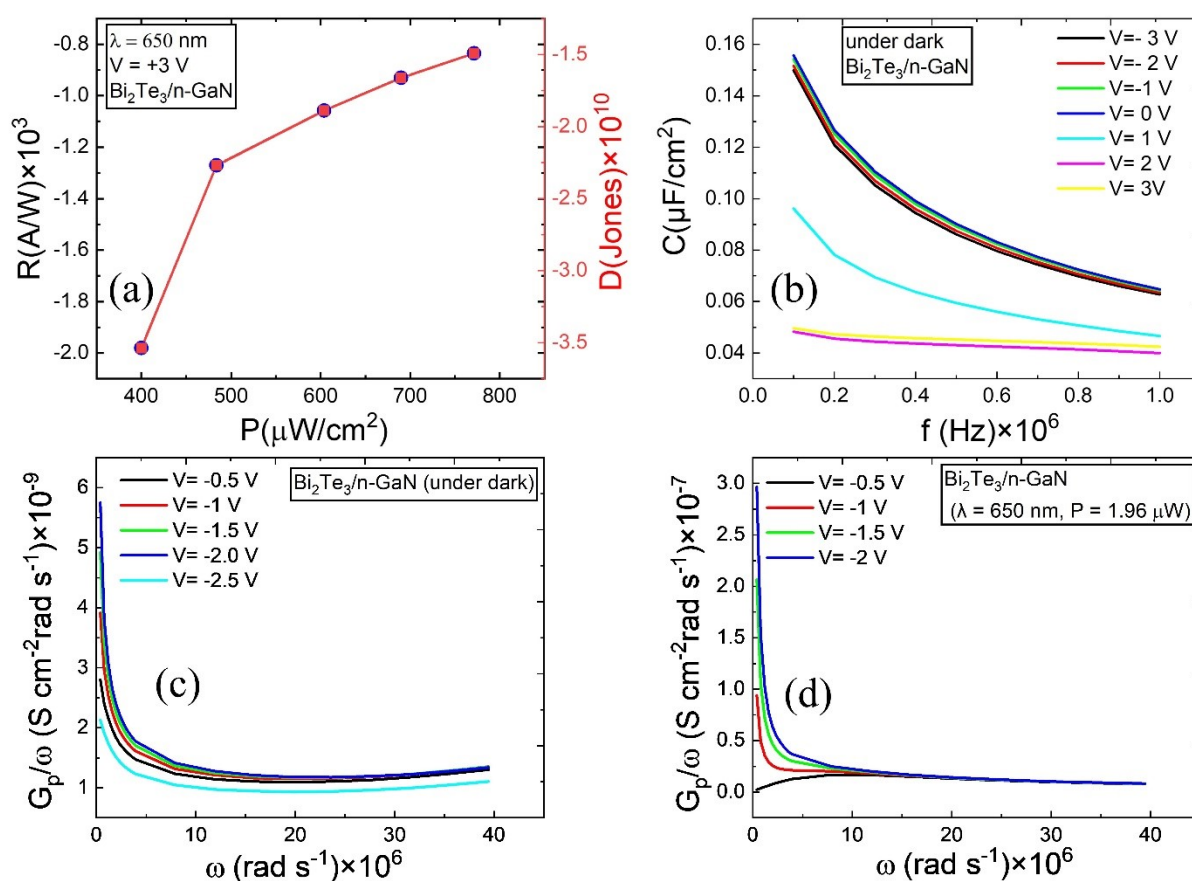


Figure S10 (a) Responsivity-power density ($R - P_D$) plot (in blue) and detectivity-power density ($D - P_D$) (in red) at a constant bias voltage of 3 V and wavelength of the incident light (λ) = 650 nm for the $\text{Bi}_2\text{Te}_3/\text{n-GaN}$ heterojunction device (b) The Capacitance-frequency ($C - f$) plot for the $\text{Bi}_2\text{Te}_3/\text{n-GaN}$ heterojunction with the bias voltage range from -3 V to $+3 \text{ V}$ (at $+1 \text{ V}$ interval), under the dark conditions (c) conductance/radial frequency (G_p/ω) versus radial frequency (ω) plot, for $\text{Bi}_2\text{Te}_3/\text{n-GaN}$ heterojunction, measured for bias voltage from -2 V to 0 V (at interval of 0.5 V) under the dark conditions (d) ($G_p/\omega - \omega$) plot for the $\text{Bi}_2\text{Te}_3/\text{n-GaN}$ heterojunction, measured for range of bias voltage from -2 V to -0.5 V (interval of 0.5 V) under the the presence of light ($\lambda = 650 \text{ nm}$, $P = 1.96 \mu\text{W}$).

7. Ultrafast Dynamics of $\text{Bi}_2\text{Te}_3/\text{n-GaN}$ heterojunction and the Bi_2Te_3 TI film

We have performed the ultrafast dynamics in Bi_2Te_3 films and its heterojunction with n-GaN. In nascent film on excitation with 410 nm pump wavelength, a transient absorption in visible region stands appearing after 1.8 ps

with maxima at ~ 540 nm and other small transient bands at ~ 710 nm and 750 nm. The transient absorption starts disappearing with appearance of ground state bleaching in the range of 550 nm to 800 nm. The GSB appears at

~ 623 nm and 764 nm. The lifetime are presented in the Table 2. In NIR region after ~ 1.1 ps time delay broad GSB is observed between 900 nm to 1600 nm with maxima ~ 1155 nm which sifted to ~ 1340 nm with delay.

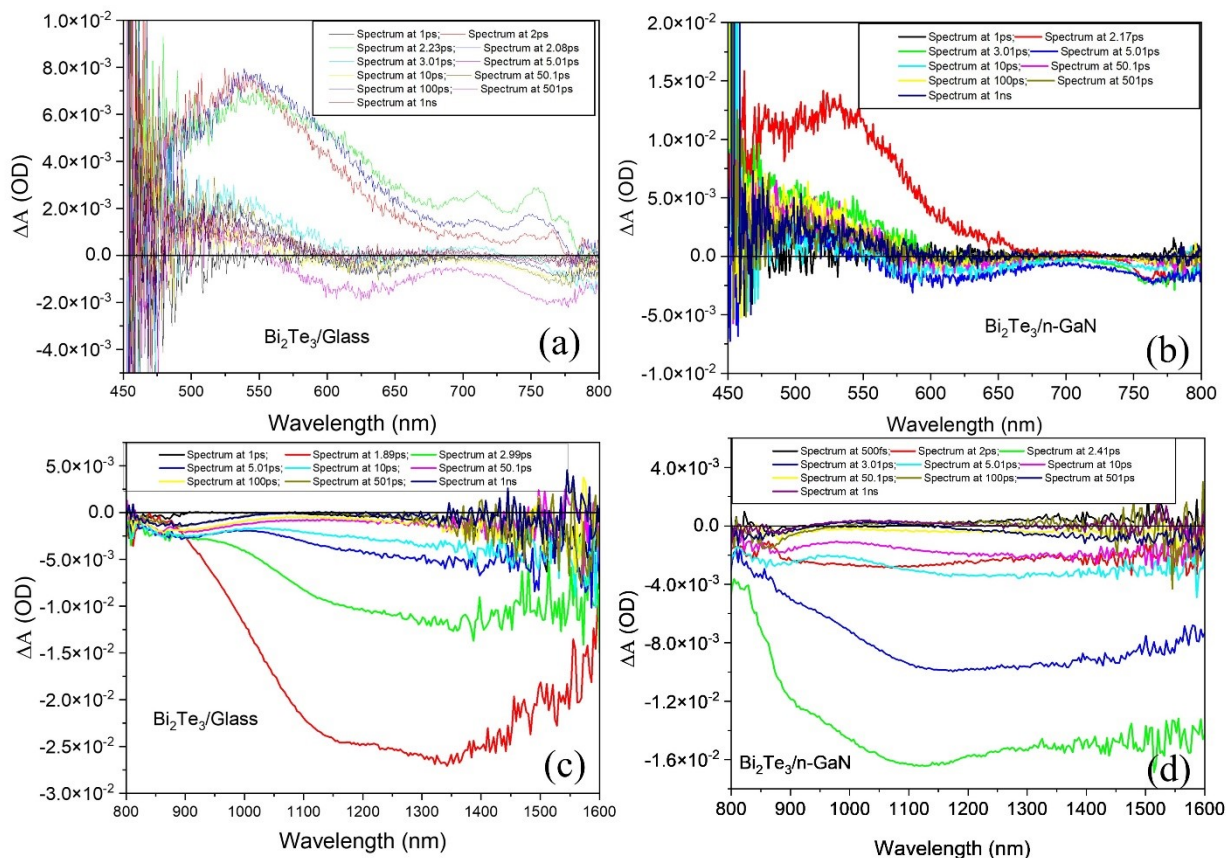


Figure S11. Transient absorption (TA) spectra showing the amplitude variation (ΔA) vs. wavelength (nm) plot in the visible range (450 nm-800 nm) for (a) Glass/ Bi_2Te_3 heterojunction (b) n-GaN/ Bi_2Te_3 heterojunction. (c&d) Shows the (ΔA) vs. wavelength (nm) plot in the near-infrared (NIR) range (800 nm-1600 nm) at different time delays for (c) Glass/ Bi_2Te_3 heterojunction (d) n-GaN/ Bi_2Te_3 heterojunction.

Table S1. Summary of the various parameters derived from the Glass/Bi₂Te₃ and n-GaN/Bi₂Te₃ transient absorption (TA) spectra and fitting on the TA results

Bi ₂ Te ₃ Film					GaN/Bi ₂ Te ₃ Heterojunction			
S.N.	Wavelength(λ) (nm)	E(ev) =1240/ λ	τ_1 (ps)	τ_2 (ps)	Wavelength (λ) (nm)	E(ev) =1240/ λ	τ_1 (ps)	τ_2 (ps)
1	540 (TA)1	2.296	1.07	-	532 (TA)1	2.331	0.6	-
2	710 (TA)1	1.746	0.73	6.4	758 (GSB)	1.636	15.8	-
3	750 (TA)1	1.653	5.7	1.57	775 (GSB)	1.600	22	-
4	623 (GSB)3	1.990	13.6	-	610 (GSB)3	2.033	11.2	-
5	764 (GSB)2	1.623	9.45	-	762 (GSB)2	1.627	2.5	-
6	1155 (GSB)4	1.074	0.78	11.7	1100 (GSB)4	1.127	0.62	10.2
7	1340 (GSB)4	0.925	0.76	14.9	-	-	-	-

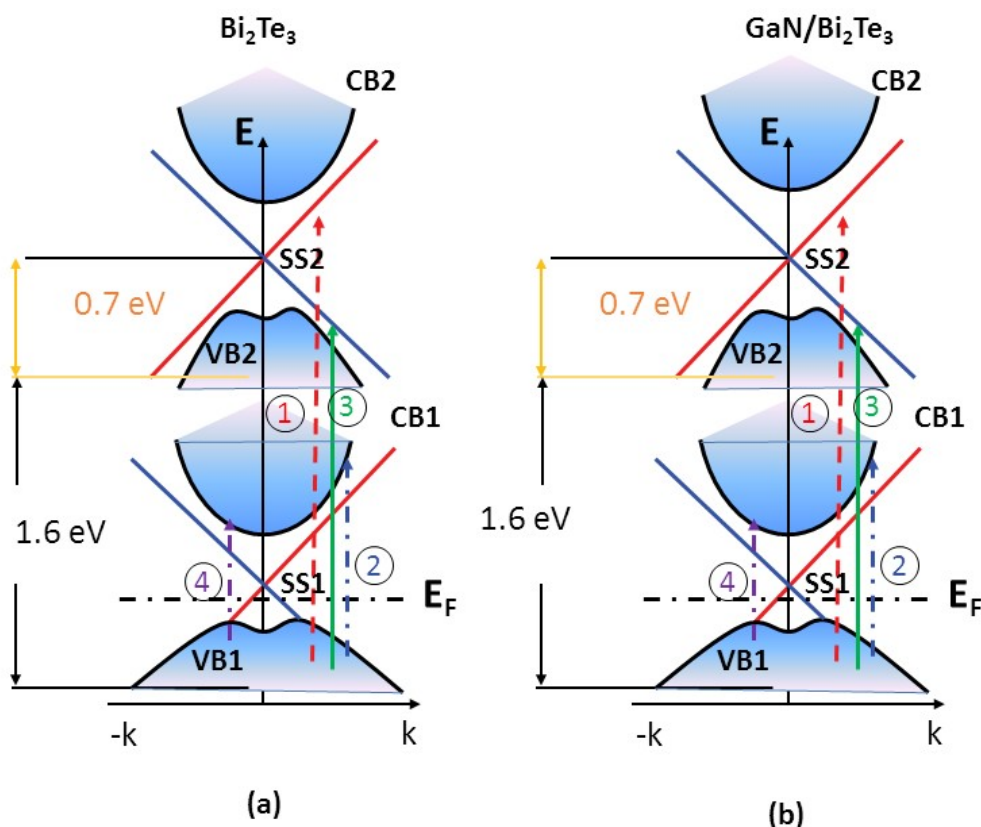


Figure S12. Shows the transition of the spin-oriented charge carriers between the different conducting states such as SS1 to SS2, CB1 to SS2, VB1 to SS1, and SS1 to CB2 respectively for (a) Glass/ Bi_2Te_3 (b) n-GaN/ Bi_2Te_3 heterojunction. The SS1, SS2 representing the two surface states, CB1, CB2 are the first and the second conduction band, VB1, VB2 first, and the second valence band.

In visible region, TA appears after 1.8ps delay time with maxima $\sim 523\text{nm}$ along with two GSB at 758nm and 775nm. These two GSB merges and new GSB appears at 610nm and 762nm after 5ps delay time. In NIR region, the GSB appears after $\sim 1.8\text{ps}$ delay time with maxima $\sim 1100\text{nm}$ and fits bi-exponentially. However, it's similar to Glass/ Bi_2Te_3 , in the heterojunction no GSB appears 1300nm range.

For the wavelength in the excitation range of 350 nm to 950 nm transition of the $\text{Bi}_2\text{Te}_3/\text{n-GaN}$ heterojunction from the first surface states (SS1) to the second surface states (SS2), the transition from the first conduction band (CB1) to the second surface state (SS2), and that from the first valence band (VB1) to the SS1, VB1 to VB2 and charge transfer from CB of GaN to CB of Bi_2Te_3 forming charge transfer (CT)¹¹ state are possible¹². But there is no visible CT state present here (Figure S12). The Dirac point of SS2 is located above the Dirac point of SS1.^{12,13,14,15–18} The spin-polarized electrons in n-GaN will inject into Bi_2Te_3 film, and injected spin-up electrons will recombine with holes in

the VB1. Therefore, the hole concentration from the bottom of the Bi_2Te_3 film get suppressed and reduces the total current contribution. Since, the total current is due to the contribution of the top and the bottom surface of the Bi_2Te_3 film i.e., the I_{e1} and I_{e2} . The suppression of the bottom surface of the current contribution enhances the total contribution of the Bi_2Te_3 film in the total current.

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